| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L1 | 0 | pin with transfer and "118"/$.ccls | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 19:10 |
| L2 | 0 | epoxy and (drop or droplet) and "118"/$.ccls | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 19:17 |
| L3 | 0 | ciardella and "118"/$.ccls | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 19:17 |
| L4 | 29 | ciardella.in. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 19:43 |
| L5 | 1951 | circuit with board and (electrode with (protruding or protrude)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 19:43 |
| L6 | 13 | circuit with board and (electrode with (protruding or protrude)) and sealant with resin | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 19:43 |
| L7 | 450 | (118/666).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L8 | 401 | (118/679).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |

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| L9 | 195 | (118/680).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L10 | 295 | (118/667).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L11 | 266 | (118/669).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L12 | 104 | (118/677).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L13 | 561 | (118/313).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L14 | 823 | (118/314).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L15 | 870 | (118/315).CCLS. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2005/09/18 20:02 |
| L16 | 78 | (L7 L8 L9 L10 L11 L12 L13 L14 L15) and (sealant or resin or paste) and (semiconductor) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 20:02 |
| L17 | 1 | ("5932012").PN. | USPAT | OR | OFF | 2005/09/18 20:02 |
| L18 | 4 | ("5932012").URPN. | USPAT | OR | ON | 2005/09/18 20:02 |

| L19 | 2 | ("5415693" \| "5437727").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2005/09/18 20:02 |
|-----|-----|-----|-----|-----|-----|-----|
| L20 | 113 | (substrate near3 (heat or heater)) and (sealant near4 (resin or paste)) and (semiconductor) and control | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/09/18 20:02 |
| L21 | 1 | ("5906682").PN. | USPAT | OR | OFF | 2005/09/18 20:02 |